

# SEMIPACK® 2

### **Rectifier Diode Modules**

#### **SKKD 250/16**

#### Features\*

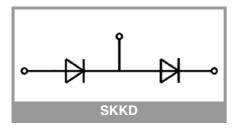
- Heat transfer through aluminum oxide ceramic insulated metal baseplate
- Hard soldered joints for high reliability
- UL recognized, file no. E63532

### **Typical Applications**

- Non-controllable rectifiers for AC/AC converters
- Line rectifiers for transistorized AC motor controllers
- Field supply for DC motors

Absolute Maximum Ratings									
Symbol	Conditions		Values	Unit					
Recitifier	Diode		•						
I <sub>FAV</sub>	sin. 180°	T <sub>c</sub> = 85 °C	255	Α					
	T <sub>j max</sub> = 135 °C	T <sub>c</sub> = 100 °C	199	Α					
I <sub>FSM</sub>	10 ms	T <sub>j</sub> = 25 °C	6600	Α					
		T <sub>j</sub> = 135 °C	6000	Α					
i <sup>2</sup> t	10 ms	T <sub>j</sub> = 25 °C	217800	A <sup>2</sup> s					
		T <sub>j</sub> = 135 °C	180000	A <sup>2</sup> s					
$V_{RSM}$	T <sub>j</sub> = 25 °C		1700	V					
$V_{RRM}$	T <sub>j</sub> = 25 °C		1600	V					
Tj			-40 135	°C					
Module									
T <sub>stg</sub>			-40 125	°C					
V <sub>isol</sub>	a.c.; 50 Hz; r.m.s.	1 min	3000	V					
		1 s	3600	V					

Characteristics										
Symbol	Conditions	min.	typ.	max.	Unit					
Diode	•									
$V_{F}$	$T_j = 25 ^{\circ}\text{C}, I_F = 750 \text{A}$				1.55	V				
$V_{F0}$	T <sub>j</sub> = 135 °C				0.77	V				
r <sub>F</sub>	T <sub>j</sub> = 135 °C				1.00	mΩ				
I <sub>R</sub>	T <sub>j</sub> = 135 °C, V <sub>RRM</sub>				9	mA				
R <sub>th(j-c)</sub>	cont.	per chip			0.13	K/W				
		per module			0.065	K/W				
R <sub>th(j-c)</sub>	sin. 180°	per chip			0.14	K/W				
	SIII. 100	per module			0.07	K/W				
Module		•								
R <sub>th(c-s)</sub>	chip			0.05		K/W				
	module			0.03		K/W				
Ms	to heatsink M5		4.25		5.75	Nm				
Mt	to terminals M6		4.25		5.75	Nm				
a					5 * 9.81	m/s²				
W				165		g				



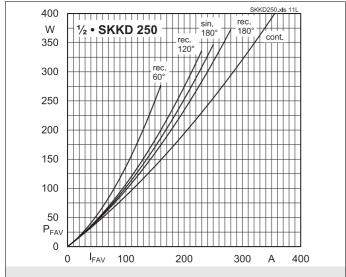


Fig. 11L: Power dissipation per diode vs. forward current

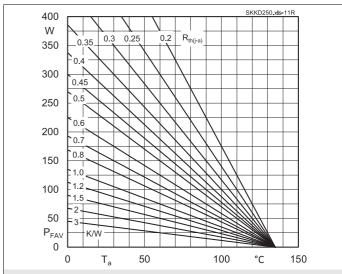


Fig. 11R: Power dissipation per diode vs. ambient temperature

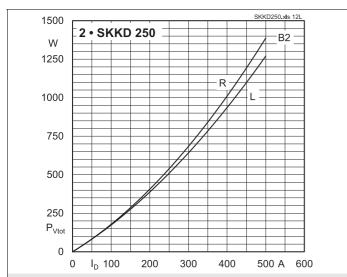


Fig. 12L: Power dissipation of two modules vs. direct current

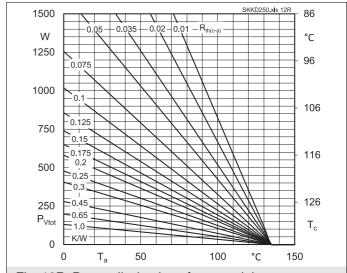


Fig. 12R: Power dissipation of two modules vs. case temperature

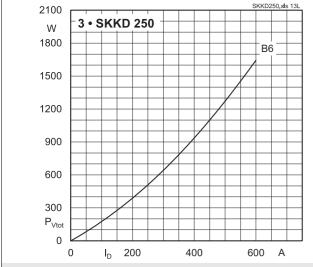


Fig. 13L: Power dissipation of three modules vs. direct current

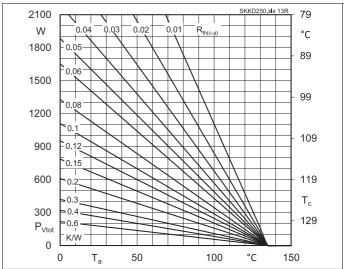


Fig. 13R: Power dissipation of three modules vs. case temperature

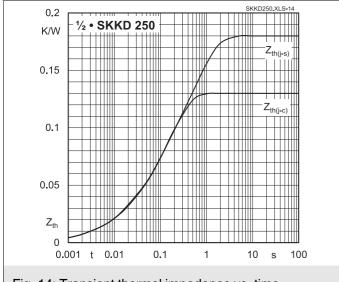


Fig. 14: Transient thermal impedance vs. time

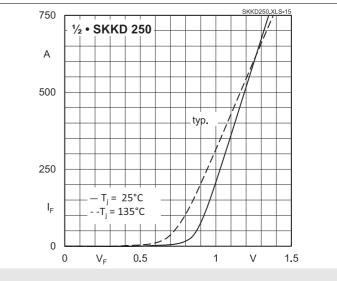
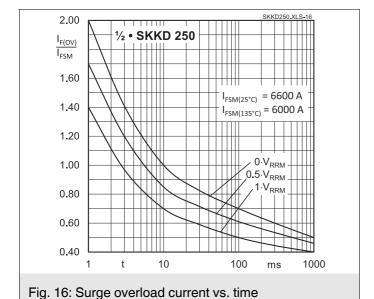
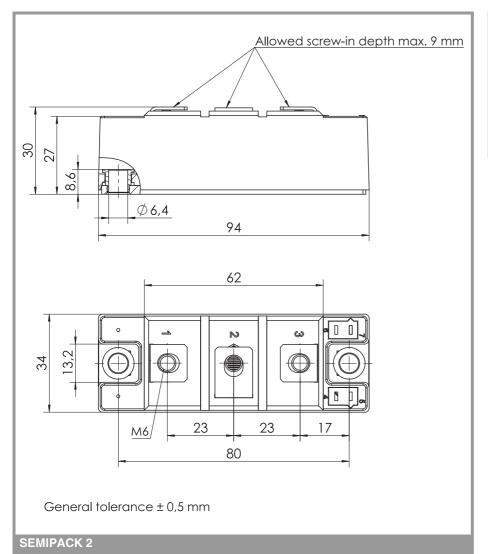
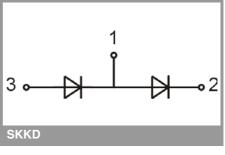


Fig. 15: Forward characteristics







This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

#### \*IMPORTANT INFORMATION AND WARNINGS

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